# UNISONIC TECHNOLOGIES CO., LTD

6N65-HC Power MOSFET

# 6A, 650V N-CHANNEL **POWER MOSFET**

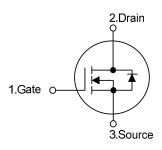
#### DESCRIPTION

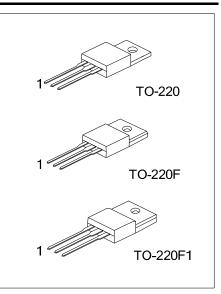
The UTC 6N65-HC is a high voltage power MOSFET designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and high rugged avalanche characteristics. This power MOSFET is usually used in high speed switching applications of switching power supplies and adaptors.

### **FEATURES**

- \*  $R_{DS(ON)}$  < 1.3  $\Omega$  @  $V_{GS}$  = 10 V,  $I_D$  = 3.0 A
- \* Fast switching capability
- \* Avalanche energy tested
- \* Improved dv/dt capability, high ruggedness

## **SYMBOL**

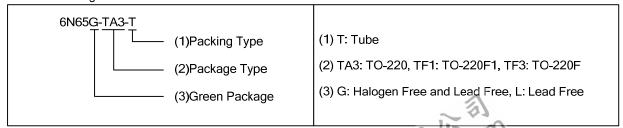




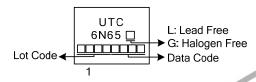
### ORDERING INFORMATION

Ordering Number		Daakana	Pin Assignment			Docking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
6N65L-TA3-T	6N65G-TA3-T	TO-220	G	D	S	Tube	
6N65L-TF1-T	6N65G-TF1-T	TO-220F1	G	D	S	Tube	
6N65L-TF3-T	6N65G-TF3-T	TO-220F	G	D	S	Tube	

Note: Pin Assignment: G: Gate S: Source D: Drain



### **MARKING**



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# ■ ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		$V_{DSS}$	650	<b>&gt;</b>
Gate-Source Voltage		$V_{GSS}$	±30	<b>&gt;</b>
Continuous Drain Current		$I_{D}$	6	Α
Pulsed Drain Current (Note 2)		I <sub>DM</sub>	24	Α
Avalanche Energy	Single Pulsed (Note 3)	E <sub>AS</sub>	68	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	2.8	V/ns
Power Dissipation	TO-220	Б.	125	W
	TO-220F/TO-220F1	$P_D$	40	W
Junction Temperature		TJ	+150	°C
Storage Temperature		T <sub>STG</sub>	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L = 17mH,  $I_{AS}$  = 2.82A,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25°C
- 4.  $I_{SD} \le 6.0A$ , di/dt  $\le 200A/\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25^{\circ}C$

# **■ THERMAL DATA**

PARAMETER		SYMBOL	RATING	UNIT
Junction to Ambient		$\theta_{JA}$	62.5	°C/W
Junction to Case	TO-220	0	1	°C/W
	TO-220F/TO-220F1	$\theta_{JC}$	3.2	°C/W



# ELECTRICAL CHARACTERISTICS (T<sub>J</sub> =25°C, unless otherwise specified)

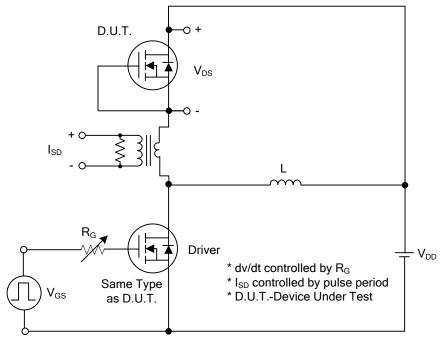
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV <sub>DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	650			V
Drain-Source Leakage Current		I <sub>DSS</sub>	$V_{DS} = 650V, V_{GS} = 0V$			10	μΑ
Gate- Source Leakage Current	Forward		$V_{GS} = 30V, V_{DS} = 0V$			100	nA
	Reverse		$V_{GS} = -30V, V_{DS} = 0V$			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.0	V
Static Drain-Source On-State Resistance		R <sub>DS(ON)</sub>	$V_{GS} = 10V, I_D = 3.0A$			1.3	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance		C <sub>ISS</sub>			1050		pF
Output Capacitance		Coss	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0 MHz		337		рF
Reverse Transfer Capacitance		C <sub>RSS</sub>			94		pF
SWITCHING CHARACTERISTIC	S	_				ā.	_
Total Gate Charge (Note 1)		$Q_G$	V <sub>DS</sub> =250V, V <sub>GS</sub> =10V, I <sub>D</sub> =6.0A, I <sub>D</sub> =100μA (Note 1, 2)		32		nC
Gate-Source Charge		$Q_GS$			11.2		nC
Gate-Drain Charge		$Q_{GD}$	I <sub>D</sub> -100μA (Note 1, 2)		9.6		nC
Turn-On Delay Time (Note 1)		t <sub>D(ON)</sub>			17		ns
Turn-On Rise Time		t <sub>R</sub>	$V_{DD}$ =30V, $V_{GS}$ =10V, $I_{D}$ =6.0A,		21		ns
Turn-Off Delay Time		t <sub>D(OFF)</sub>	$R_G = 25\Omega$ (Note 1, 2)		113		ns
Turn-Off Fall Time		t <sub>F</sub>			37		ns
DRAIN-SOURCE DIODE CHARA	CTERISTIC	S AND MAX	(IMUM RATINGS			ā.	_
Maximum Continuous Drain-Source	ce Diode					6	Α
Forward Current		l <sub>S</sub>				O	A
Maximum Pulsed Drain-Source Diode		I <sub>SM</sub>				24	Α
Forward Current						24	A
Drain-Source Diode Forward Voltage		$V_{SD}$	I <sub>S</sub> =6.0A , V <sub>GS</sub> =0V			1.4	V
Body Diode Reverse Recovery Time		t <sub>rr</sub>	I <sub>S</sub> =6.0A , V <sub>GS</sub> =0V		312		ns
Body Diode Reverse Recovery Charge		Qrr	di/dt=100A/μs		2.44		μC

Notes: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle ≤ 2%.

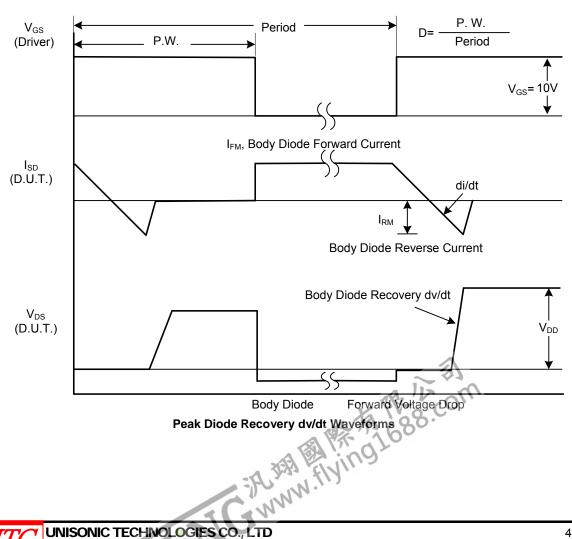
2. Essentially independent of operating temperature.



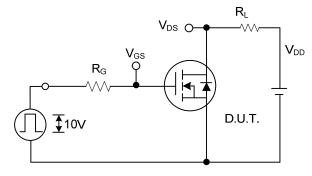
# **TEST CIRCUITS AND WAVEFORMS**



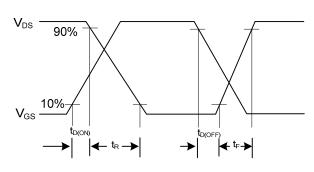
Peak Diode Recovery dv/dt Test Circuit



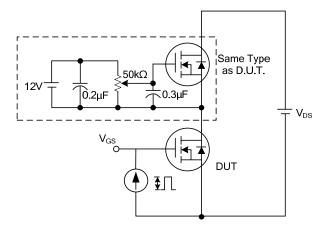
# **TEST CIRCUITS AND WAVEFORMS (Cont.)**



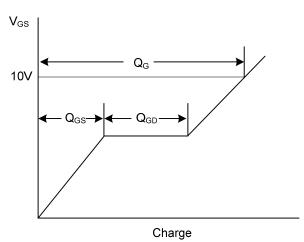
**Switching Test Circuit** 



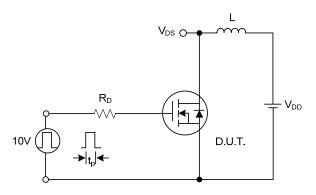
**Switching Waveforms** 



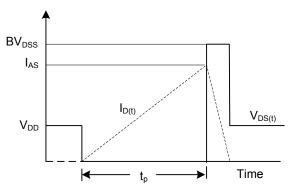
**Gate Charge Test Circuit** 



**Gate Charge Waveform** 

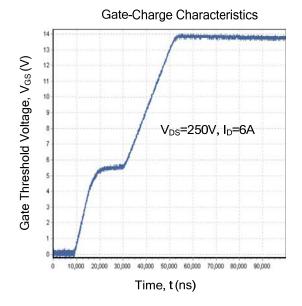


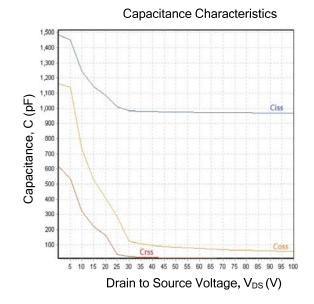
**Unclamped Inductive Switching Test Circuit** 



**Unclamped Inductive Switching Waveforms** 

# TYPICAL CHARACTERISTICS





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